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Part Number: 0736441217

Status: **Active**

Overview: **HDM Backplane Connector System**

HDM Board-to-Board Backplane Header, Vertical, SMC, Press-Fit, Guide Post Location **Description:**

A, Polarizing Key Position N/A, 144 Circuits, Mating Length 6.00mm

Documents:

Packaging Specification PK-70873-0818-001 (PDF) 3D Model

RoHS Certificate of Compliance (PDF) **Drawing (PDF)**

3D Model (PDF)

Agency Certification

LR19980 **CSA** UL E29179

General

Product Family Backplane Connectors

Series 73644 **Application** Backplane

Comments Standard Press-Fit Component Type **PCB** Header

Overview **HDM Backplane Connector System**

Product Name HDM

UPC 800754345347

Physical

Circuits (Loaded) 144 Circuits (maximum) 144

Color - Resin Black, Natural

Durability (mating cycles max) 250 First Mate / Last Break Nο Flammability 94V-0 Guide to Mating Part Yes Keying to Mating Part None

Material - Metal Phosphor Bronze, Stainless Steel

Material - Plating Mating Gold Material - Plating Termination Gold

Material - Resin High Temperature Thermoplastic

Net Weight 9.026/g Number of Columns 24

Open Pin Field Number of Pairs

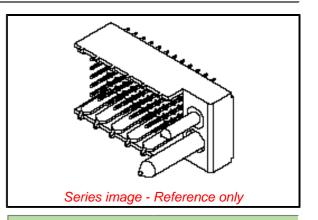
Number of Rows Orientation Vertical PC Tail Length 3.50mm PCB Locator No **PCB** Retention Yes PCB Thickness - Recommended 2.50mm Packaging Type Tube Pitch - Mating Interface 2.00mm Pitch - Termination Interface 2.00mm

Plating min - Mating 0.762um Plating min - Termination 0.051um Polarized to PCB Nο Stackable Yes Surface Mount Compatible (SMC)

Temperature Range - Operating -55° to +105°C

Termination Interface: Style Through Hole - Compliant Pin

Yes



EU ELV

Not Relevant

EU RoHS China RoHS

Compliant **REACH SVHC** Not Contained Per -D(2020)9139-DC (19 Jan 2021)

Halogen-Free **Status**

Low-Halogen

For more information, please visit Contact US

China ROHS Green Image Not Relevant ELV RoHS Phthalates Not Contained

Search Parts in this Series

73644 Series

Mates With

73632 HDM+ Board-to-Board Daughtercard Receptacle. 73780 HDM Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ

Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global

Description Product # **Extraction Tool** 621001000

Electrical

Current - Maximum per Contact 1.0A
Data Rate 1.0 Gbps
Real Signals (per 25mm) 75

Real Signals (per 25mm) 75
Shielded No
Voltage - Maximum 250V AC

Solder Process Data

Lead-freeProcess Capability N/A

Material Info

Reference - Drawing Numbers

Packaging Specification PK-70873-0818-001

Sales Drawing SDA-73644-XXXX-001, SDA-73644-XXXX-002

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